

2SB1027

Silicon PNP Epitaxial

HITACHI

ADE-208-1038 (Z)

1st. Edition

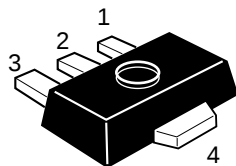
Mar. 2001

Application

Low frequency amplifier

Outline

UPAK



- 1. Base
- 2. Collector
- 3. Emitter
- 4. Collector (Flange)

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Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-180	V
Collector to emitter voltage	V_{CEO}	-120	V
Emitter to base voltage	V_{EBO}	-5	V
Collector current	I_C	-1.5	A
Collector peak current	$i_{C(peak)}^{*1}$	-3	A
Collector power dissipation	P_C^{*2}	1	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \leq 10$ ms, Duty cycle $\leq 20\%$

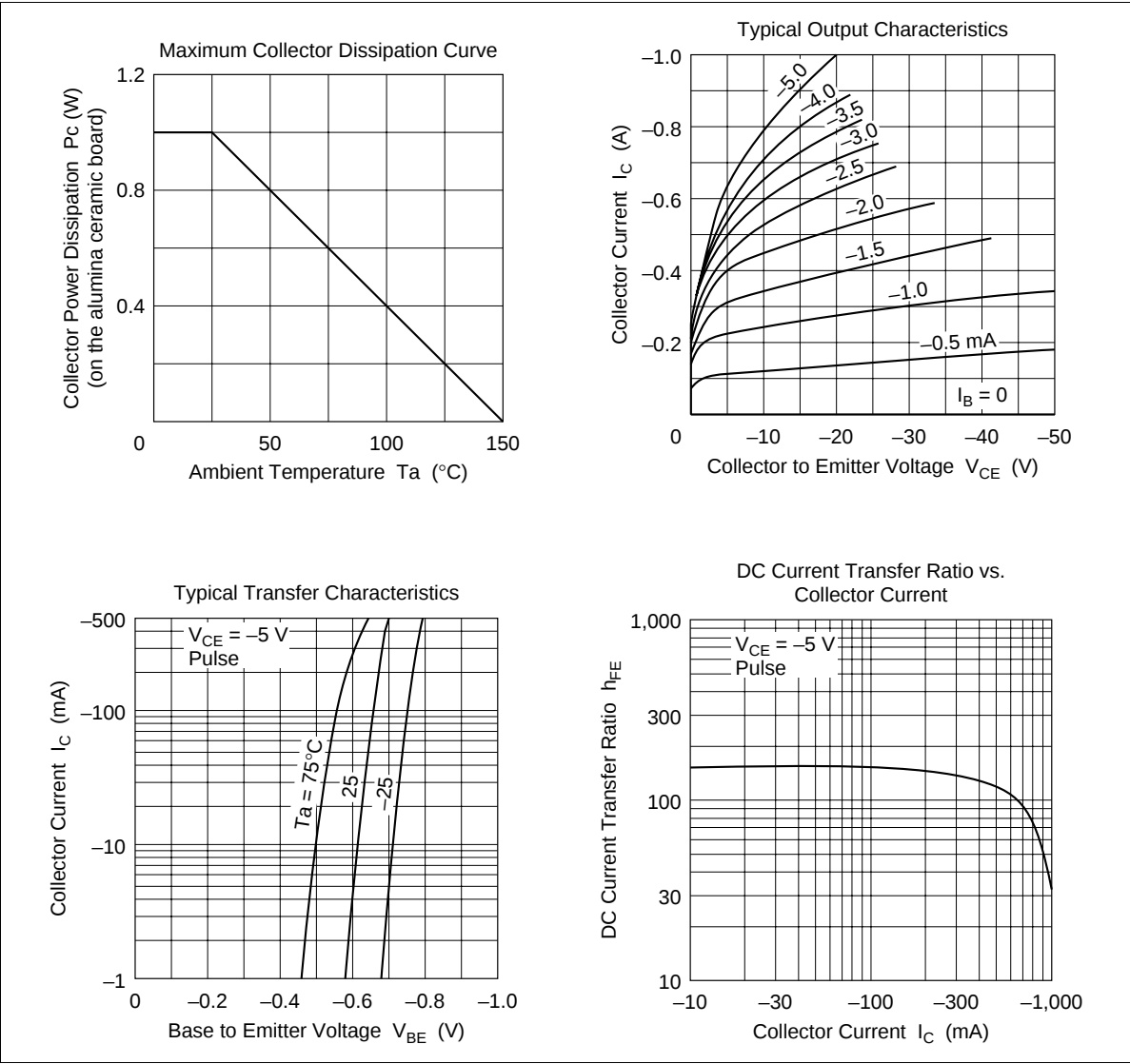
2. Value on the alumina ceramic board (12.5 × 20 × 0.7 mm)

Electrical Characteristics (Ta = 25°C)

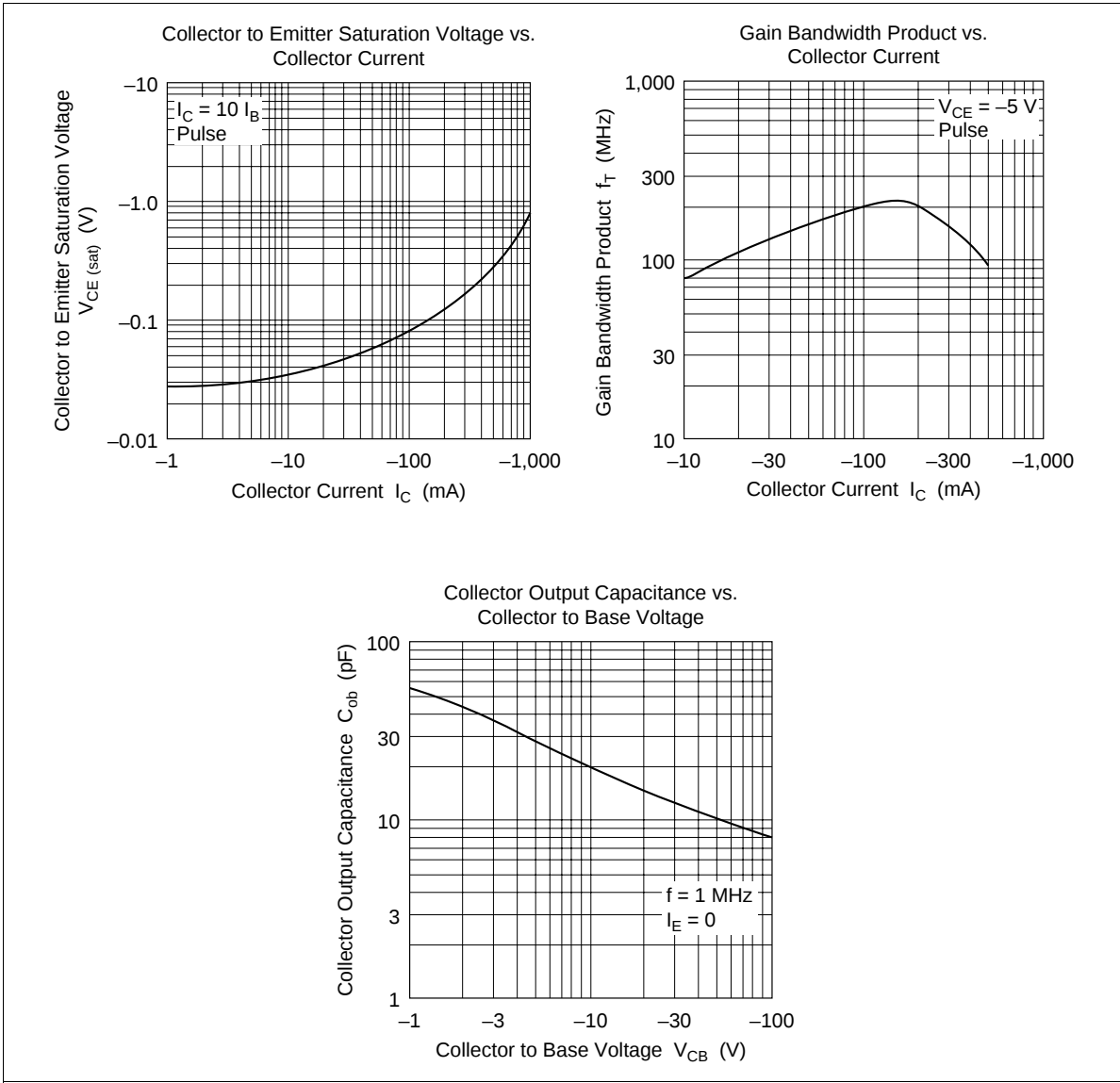
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-180	—	—	V	$I_C = -1$ mA, $I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-120	—	—	V	$I_C = -10$ mA, $R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-5	—	—	V	$I_E = -1$ mA, $I_C = 0$
Collector cutoff current	I_{CBO}	—	—	-10	μA	$V_{CB} = -160$ V, $I_E = 0$
DC current transfer ratio	h_{FE1}^{*1}	60	—	320		$V_{CE} = -5$ V, $I_C = -0.15$ A, pulse
	h_{FE2}	30	—	—		$V_{CE} = -5$ V, $I_C = -0.5$ A, pulse
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	-1.0	V	$I_C = -0.5$ A, $I_B = -50$ mA, Pulse
Base to emitter voltage	V_{BE}	—	—	-0.9	V	$V_{CE} = -5$ V, $I_C = -0.15$ A, pulse

Note: 1. The 2SB1027 is grouped by h_{FE1} as follows.

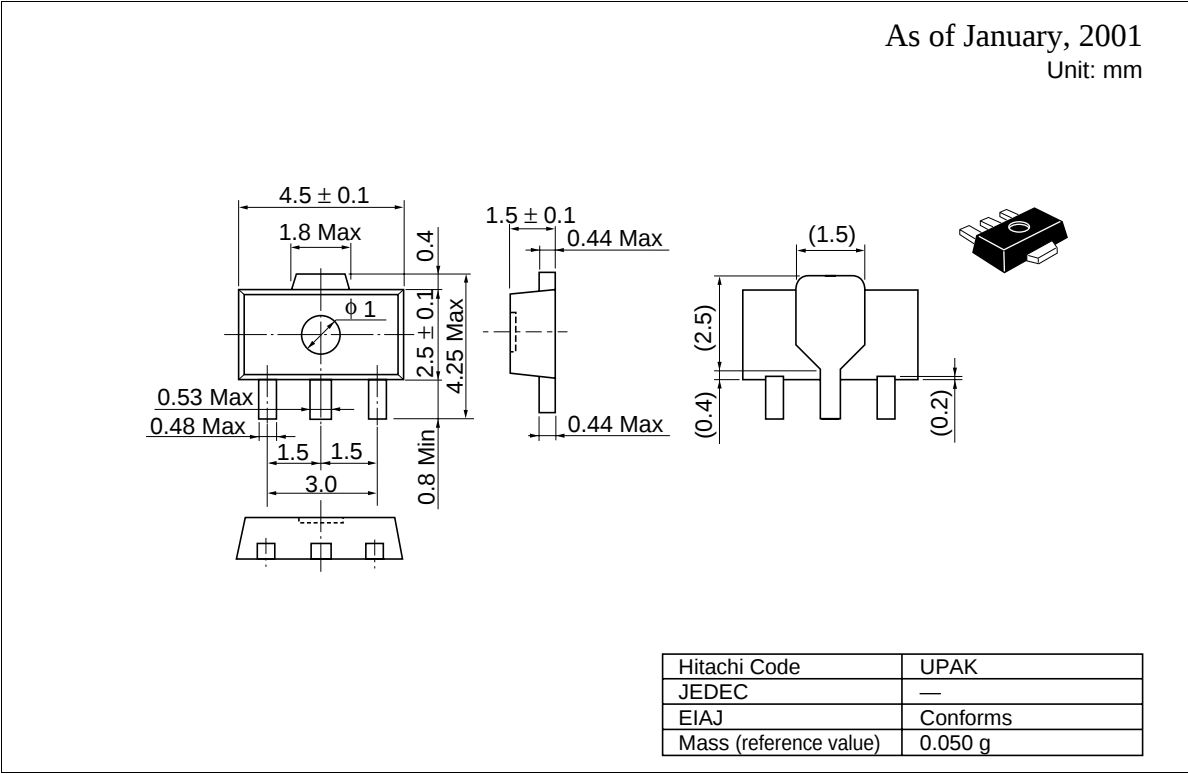
Mark	EH	EJ	EK
h_{FE1}	60 to 120	100 to 200	160 to 320



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Package Dimensions



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